

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10657505			
<b>Filing Date:</b>	08-Sep-2003			
<b>Title of Invention:</b>	Method of manufacturing a contact interconnection layer containing a metal and nitrogen by atomic layer deposition for deep sub-micron semiconductor technology			
<b>First Named Inventor:</b>	Chii-Ming Wu			
<b>Filer:</b>	David M. Odell/Denise Wilson			
<b>Attorney Docket Number:</b>	TS01-1247			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120